

## AMENDMENTS TO THE CLAIMS

Claims 1-17 (Cancelled)

18. (Currently Amended) An apparatus, comprising:
  - a heat sink comprising a thermoelectric (TEC) module having a polarity, the polarity capable of being adjusted to direct or redirect heat in one or more directions to melt or un-melt a thermal interface material (TIM); and  
a-the thermal interface material (TIM) coupled with the heat sink, the TIM receiving a redirected-the heat in the heat sink upon changing of the polarity to melt the TIM up to an acceptable melt level to be applied to or removed from the heat sink.
19. (Currently Amended) The apparatus of claim 18, wherein the TIM is applied to or removed from at one or more of a base of the heat sink, a thermal gap between the heat sink, and a heat source.
20. (Currently Amended) The apparatus of claim 18, wherein the TIM is applied via an application device, the application device including includes one or more of an epoxy dispenser machine and a vacuum suction cup.
21. (Previously Presented) The apparatus of claim 18, wherein the adjusting of the polarity comprises reversing of the polarity.
22. (Currently Amended) The apparatus of claim 21, wherein the adjusting of the polarity ~~comprises~~is performed via one or more of reversing terminals of the TEC module, and adjusting a power source.
23. (Currently Amended) A system, comprising:
  - a storage medium;
  - a integrated circuit (IC) device coupled with the storage medium;

a heat sink coupled with the IC device, the heat sink comprising a thermoelectric (TEC) module having a polarity, the polarity capable of being adjusted to direct or redirect heat in one or more directions to melt or un-melt a thermal interface material (TIM); and

athe thermal interface material (TIM) coupled with the heat sink and the IC device, the TIM receiving a redirectedthe heat in the heat sink upon changing of the polarity to melt the TIM up to an acceptable melt level to be applied to or removed from the heat sink.

24. (Currently Amended) The system of claim 23, wherein the TIM is applied to or removed from one or more of a base of the heat sink, a thermal gap between the heat sink, and a heat source.
25. (Currently Amended) The system of claim 23, wherein the TIM is applied via an application device, the application device comprising comprises one or more of an epoxy dispenser machine and a vacuum suction cup.
26. (Original) The system of claim 23, wherein the changing of the polarity comprises reversing of the polarity.
27. (Currently Amended) The system of claim 26, wherein the reversing of the polarity is performed byvia one or more of reversing terminals of the TEC module, using a device to change the polarity of the TEC module, and adjusting a power source.
28. (Previously Presented) The system of claim 23, wherein the IC device comprises one or more of a microprocessor, a microcontroller, a graphics processor, a digital signal processor (DSP), a complex instruction set computing (CISC) processor, a

reduced instruction set computing (RISC) processor, and a very long instruction word (VLIW) processor.